

TE Internal #: 829540-9

PCB Mount Header, Right Angle, Board-to-Board, 18 Position, 2.54 mm [.1in] Centerline, Partially Shrouded, Gold Flash, Printed Circuit

Board

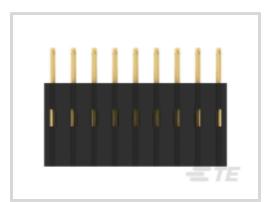
View on TE.com >

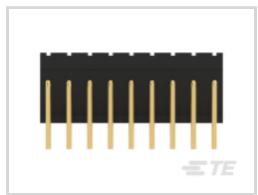


Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle
Connector System: Board-to-Board

Number of Positions: 18

Centerline (Pitch): 2.54 mm [.1 in]

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

PCB Mount Orientation	Right Angle
Number of Positions	18
Board-to-Board Configuration	Perpendicular

Contact Features

Contact Mating Area Plating Material	Gold Flash
Contact Mating Area Plating Material Thickness	.8 μm[31.5 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A

Termination Features



Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Color	Black
Housing Material	PA 4.6
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Usage Conditions	
Operating Temperature Range	-65 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Carton

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not reviewed for solder process capability



Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Customers Also Bought























Documents

Product Drawings

2X9P MOD II SHROUDED HEADER, RT ANG

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_829540-9_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_829540-9_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_829540-9_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

AMPMODU Interconnetion System

English

AMPMODU Interconnetion System